

SN54BCT760, SN74BCT760 OCTAL BUFFERS/DRIVERS WITH OPEN-COLLECTOR OUTPUTS

SCBS034B – JULY 1989 – REVISED NOVEMBER 1993

- Open-Collector Version of 'BCT244
- Open-Collector Outputs Drive Bus Lines or Buffer Memory Address Registers
- ESD Protection Exceeds 2000 V Per MIL-STD-883C Method 3015
- Packages Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (J, N)

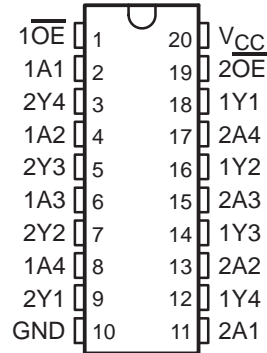
description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

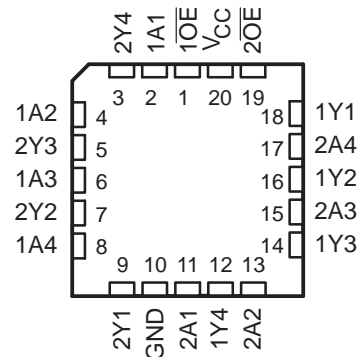
The 'BCT760 is organized as two 4-bit buffers/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

The SN54BCT760 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74BCT760 is characterized for operation from 0°C to 70°C .

SN54BCT760 . . . J OR W PACKAGE
SN74BCT760 . . . DW OR N PACKAGE
(TOP VIEW)



SN54BCT760 . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each buffer)

| INPUTS | | OUTPUT Y |
|-----------------|---|-------------|
| \overline{OE} | A | |
| L | H | H |
| L | L | L |
| H | X | H |

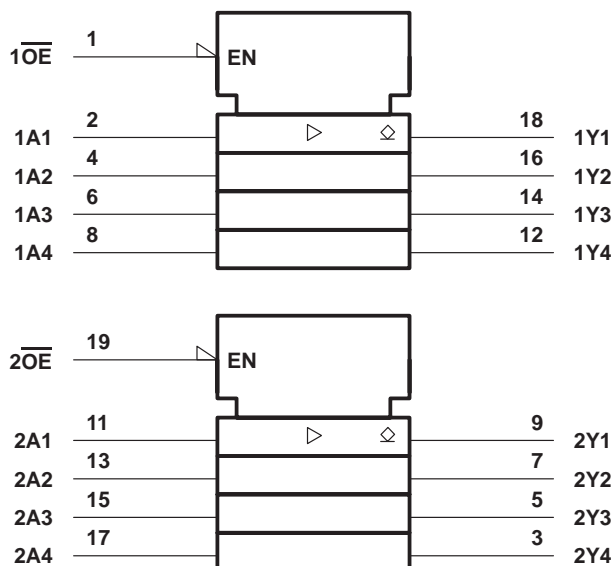
SN54BCT760, SN74BCT760

OCTAL BUFFERS/DRIVERS

WITH OPEN-COLLECTOR OUTPUTS

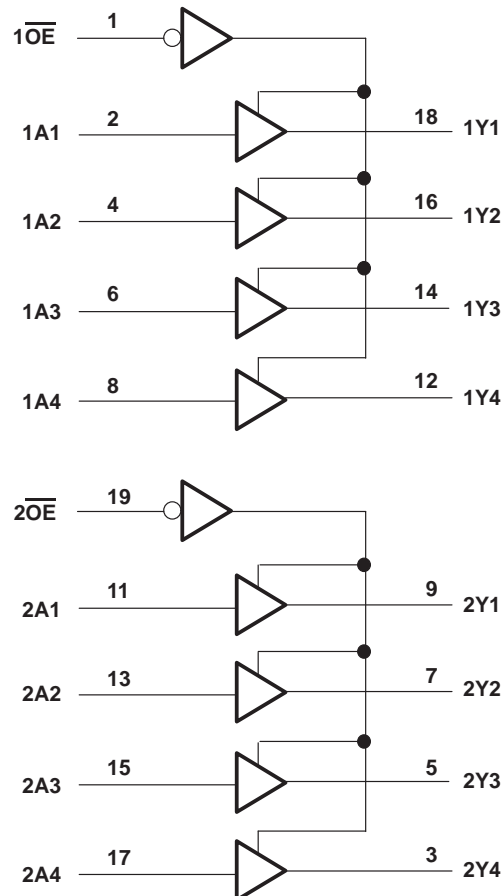
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| | |
|---|---------------------|
| Supply voltage range, V_{CC} | – 0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | – 0.5 V to 7 V |
| Input current range, I_I | – 30 mA to 5 mA |
| Voltage range applied to any output in the disabled or power-off state, V_O | – 0.5 V to 5.5 V |
| Voltage range applied to any output in the high state, V_O | – 0.5 V to V_{CC} |
| Current into any output in the low state: SN54BCT760 | 96 mA |
| SN74BCT760 | 128 mA |
| Operating free-air temperature range: SN54BCT760 | – 55°C to 125°C |
| SN74BCT760 | 0°C to 70°C |
| Storage temperature range | – 65°C to 150°C |

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The negative input voltage rating may be exceeded if the input clamp current rating is observed.

recommended operating conditions

| | | SN54BCT760 | | | SN74BCT760 | | | UNIT |
|----------|--------------------------------|------------|-----|-----|------------|-----|-----|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| V_{OH} | High-level output voltage | | | 5.5 | | | 5.5 | V |
| I_{IK} | Input clamp current | | | –18 | | | –18 | mA |
| I_{OL} | Low-level output current | | | 48 | | | 64 | mA |
| T_A | Operating free-air temperature | –55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | SN54BCT760 | | | SN74BCT760 | | | UNIT |
|-----------|--|--------------------------|------------|------|------|------------|------|------|------|
| | | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| V_{IK} | $V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$ | | | | –1.2 | | | –1.2 | V |
| V_{OL} | $V_{CC} = 4.5\text{ V}$ | $I_{OL} = 48\text{ mA}$ | | 0.38 | 0.55 | | | | V |
| | | $I_{OL} = 64\text{ mA}$ | | | | 0.42 | 0.55 | | |
| I_I | $V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$ | | | | 0.1 | | | 0.1 | mA |
| I_{IH} | $V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$ | | | | 20 | | | 20 | μA |
| I_{IL} | $V_{CC} = 5.5\text{ V}$, $V_I = 0.5\text{ V}$ | | | | –1 | | | –1 | mA |
| I_{OH} | $V_{CC} = 4.5\text{ V}$, $V_{OH} = 5.5\text{ V}$ | | | | 0.1 | | | 0.1 | mA |
| I_{CC} | $V_{CC} = 5.5\text{ V}$, Outputs open | Outputs high | | 21 | 33 | | 21 | 33 | mA |
| | | Outputs low | | 48 | 76 | | 48 | 76 | |
| | | \overline{OE} disabled | | 6 | 10 | | 6 | 10 | |
| C_i | $V_{CC} = 5\text{ V}$, $V_I = 2.5\text{ V}$ or 0.5 V | | | 6 | | | 6 | | pF |
| C_o | $V_{CC} = 5\text{ V}$, $V_I = 2.5\text{ V}$ or 0.5 V | | | 10 | | | 10 | | pF |

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

switching characteristics (see Note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | VCC = 5 V, CL = 50 pF, RL = 500 Ω, TA = 25°C | | | VCC = 4.5 V to 5.5 V, CL = 50 pF, RL = 500 Ω, TA = MIN to MAX‡ | | | | UNIT |
|-----------|-----------------|----------------|---|-----|------|---|------|------------|------|------|
| | | | †BCT760 | | | SN54BCT760 | | SN74BCT760 | | |
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| tPLH | Any A | Y | 6.3 | 8 | 9.5 | 6.3 | 11.1 | 6.3 | 10 | ns |
| tPHL | | | 2.1 | 4.3 | 6.5 | 2.1 | 7.7 | 2.1 | 7.2 | |
| tPLH | OE | Y | 8.6 | 13 | 15.2 | 8.6 | 18.7 | 8.6 | 17.5 | ns |
| tPHL | | | 3.2 | 6.2 | 8.9 | 3.2 | 10.4 | 3.2 | 9.9 | |

‡ For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9093801M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| 5962-9093801MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| 5962-9093801MSA | ACTIVE | CFP | W | 20 | 1 | TBD | A42 | N / A for Pkg Type |
| SN54BCT760J | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN74BCT760DW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760DWE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760DWG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760DWR | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760DWRE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760DWRG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760N | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT760NE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT760NSR | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760NSRE4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT760NSRG4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ54BCT760FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54BCT760J | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54BCT760W | ACTIVE | CFP | W | 20 | 1 | TBD | A42 | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

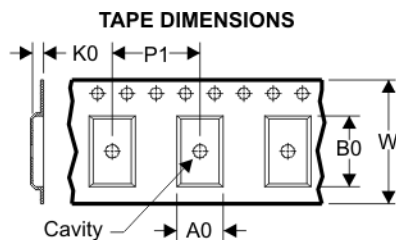
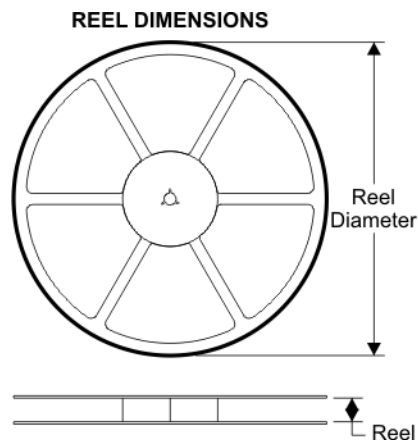
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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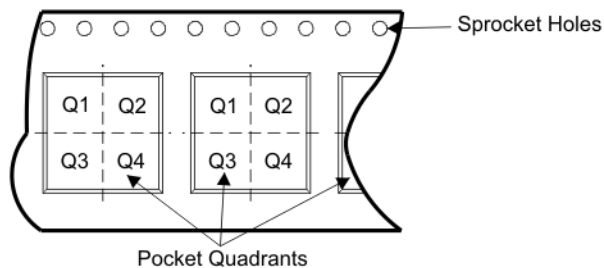
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TAPE AND REEL BOX INFORMATION



| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| Device | Package | Pins | Site | Reel Diameter (mm) | Reel Width (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|---------|------|---------|--------------------|-----------------|---------|---------|---------|---------|--------|---------------|
| SN74BCT760DWR | DW | 20 | SITE 41 | 330 | 24 | 10.8 | 13.0 | 2.7 | 12 | 24 | Q1 |

TAPE AND REEL BOX DIMENSIONS



| Device | Package | Pins | Site | Length (mm) | Width (mm) | Height (mm) |
|---------------|---------|------|---------|-------------|------------|-------------|
| SN74BCT760DWR | DW | 20 | SITE 41 | 346.0 | 346.0 | 41.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| PINS ** DIM | 14 | 16 | 18 | 20 |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



| PINS ** | 14 | 16 | 18 | 20 |
|---------------------|------------------|------------------|------------------|------------------|
| DIM | | | | |
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS-001 VARIATION | AA | BB | AC | AD |

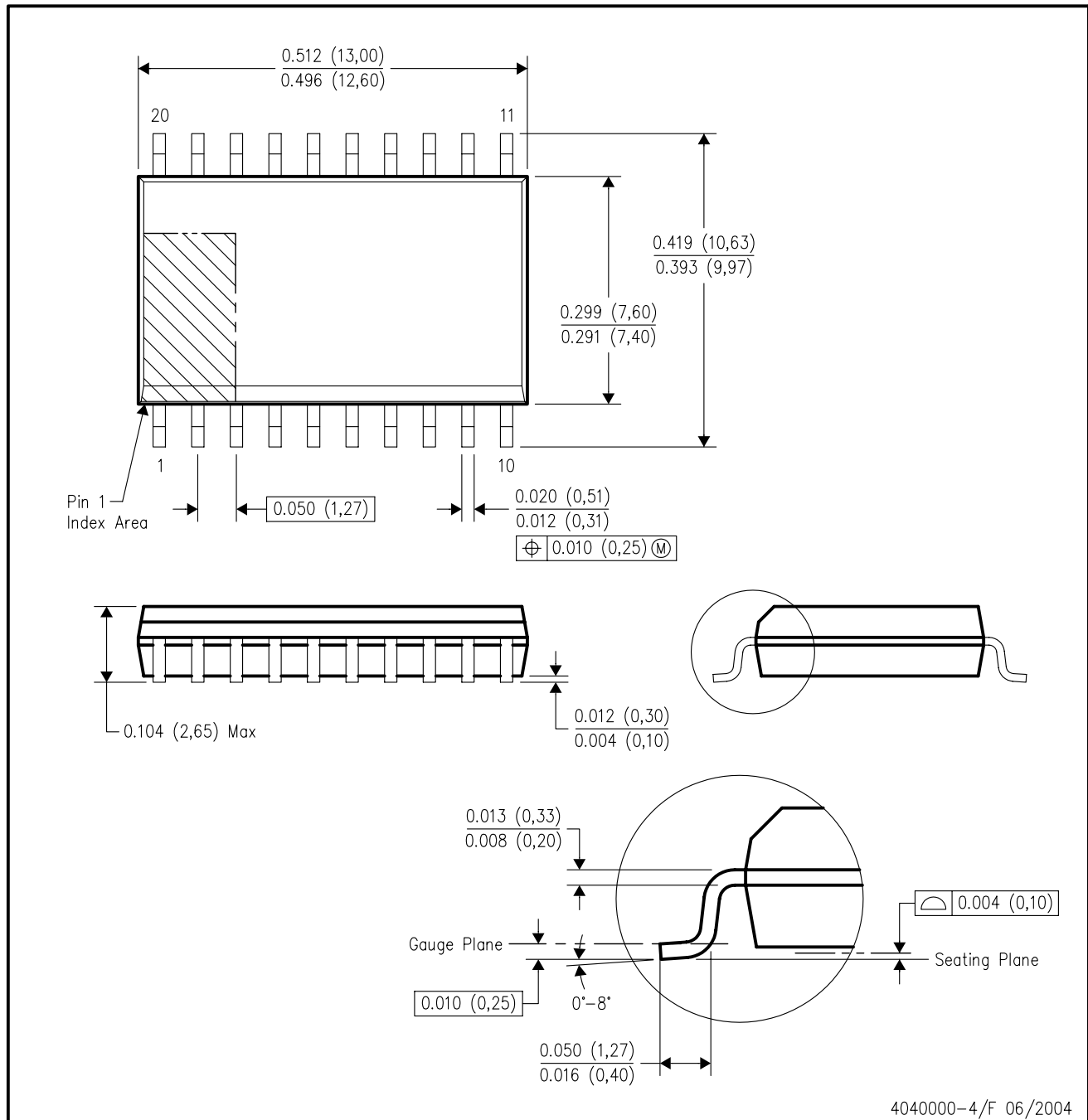


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

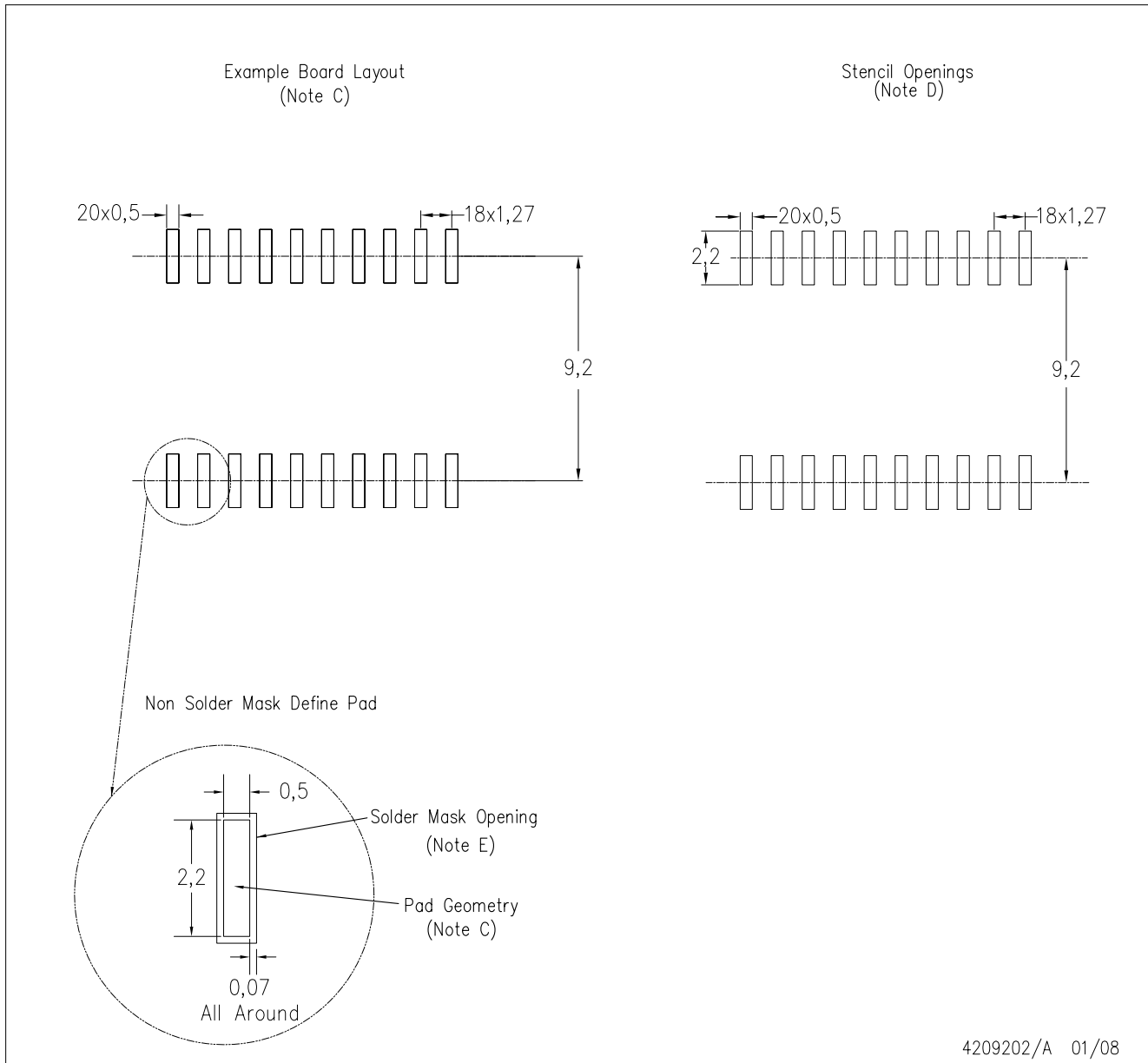
DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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